

TP600 Gap Filler Pad

Features and Benefits

- 6.0 W/m.K
- High performance
- Electrically non-conductive
- Ultra-low compression
- Excellent and easy to operate



TP600 is a high thermal conductivity material with high conformability at low pressure. It is self-adhesive on both sides. When assembled with electronic components, it exhibits lower thermal resistance and better electrical insulation characteristics under low compression force. It can work stably at -40°C~150°C and meet the flame retardant rating requirements of UL94 V0.

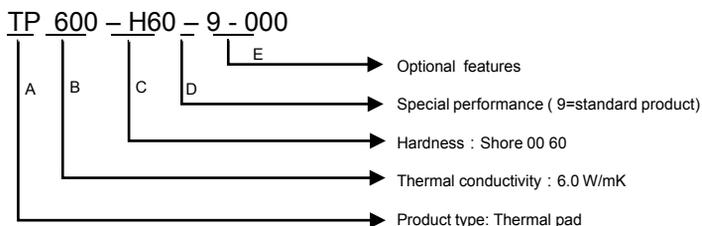
TP 600 Typical Properties		
Attribute	Value	Test Method
Composition	Ceramic filled silicone	-
Colour	Warmred	Visual
Thickness (mm)	0.5~10.0	ASTM D374
Density(g/cc)	3.285	ASTM D792
Hardness (Shore OO)	40(Thickness≤1.0 Shore OO 50)	ASTM D2240
Usage Temperature (°C)	-40~150	-
Electrical		
Breakdown Voltage(Kv/mm)	>5.0	ASTM D149
Dielectric Constant@1MHz	7.9	ASTM D150
Volume Resistivity(Ω.cm)	10 ¹²	ASTM D257
Flammability Rating	V-0	UL 94
Thermal		
Thermal Conductivity(W/m.K)	6.0	ISO22007-2
Thermal Resistance (°C -in ² /W, @20psi, 1mm)	0.138	ASTM D5470

*Thickness tolerance +/- 10%

Typical Applications

- Voltage regulation modules (VRMs)
- ASICs and DSPs
- Modules with high thermal conductivity requirements
- High-speed large storage drive
- High-calorie BGAs
- CD ROM/DVD ROM
- Network communication equipment

Product Nomenclature



Standard size: 200x400mm. May be die cut into various sizes or shapes according to customer's specifications. The thickness selected should be 15 to 20% thicker than highest tolerance gap to ensure material fills all voids and wets out mating surfaces.